

Title (en)  
IMPROVED TEST STRUCTURES AND METHODS FOR INSPECTING AND UTILIZING THE SAME

Title (de)  
VERBESSERTE TESTSTRUKTUREN, DEREN INSPEKTIONSMETHODE UND VERWENDUNG

Title (fr)  
STRUCTURES D'ESSAI AMELIOREES ET LEURS PROCEDES D'INSPECTION ET D'UTILISATION

Publication  
**EP 1328971 A2 20030723 (EN)**

Application  
**EP 00989275 A 20001214**

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Abstract (en)  
[origin: WO0180304A2] A sample is inspected by moving to a first field associated with a first group of test structures, which are partially within the first field, which is scanned to determine whether there are any defects present. If defects are present a specific defect location is determined by repeatedly stepping to areas and scanning such areas within the first group of test structures. In a second method, a sample is scanned in a first direction and in a second direction at an angle to the first direction with at least one particle beam. The number of defects per area of the sample are found as a result of the first scan, and the position of one or more of the found defects is determined from the second scan. A semiconductor die includes test structure located entirely within a scanning area and only partially within the scanning area. The test structures are arranged so that a scan of the scanning area results in detection of defects outside of the scanning area.

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